

## Bill of Materials

TIDA-00604

Item	Qty	Reference	Value	Part Description	Manufacturer	Manufacturer	Alternate Part	PCB Footprint	Note
						Part Number			
1	9	C1, C2, C4, C9-C11, C14-C16	10μF	Capacitor, ceramic, 6.3 V, X5R, 10%	TDK	C2012X5R0J106K	-	0805	
2	2	C12, C13	2.2μF	Capacitor, ceramic, 6.3 V, X5R, 10%	TDK	C1608X5R0J225K	-	0603	
3	4	C3, C6, C7, C17	1.0μF	Capacitor, ceramic, 6.3 V, X5R, 10%	TDK	C1608X5R0J105K	-	0603	
4	1	C5	1500pF	Capacitor, ceramic, 50 V, X7R, 10%	TDK	C1608X7R1H152K	-	0603	
5	2	C8, C18	2.2μF	Capacitor, ceramic, 6.3 V, X5R, 10%	TDK	C1608X5R0J225K	-	0603	
6	16	J1-J6, J9-J18	-	Header, 2 pin, 100 mil spacing, (36-pin strip)	Sullins	PTC36SAAN	-	0.100 x 2	
				Connector, Male straight 2c5 pin, 100 mil spacing, 4					
7	1	J20	-	wall	3M	2510-6002UB	-	0.33 x 0.788	
8	2	J7, J8	-	Header, 4 pin, 100 mil spacing, (36-pin strip)	Sullins	PTC36SAAN	-	0.100 x 4	
9	9	JP1-JP9	-	Header, 3 pin, 100 mil spacing, (36-pin strip)	Sullins	PTC36SAAN	-	0.100 x 3	
10	2	L1, L2	2.2μH	Inductor, SMT, 1.72A, 59 mW	TDK	VLCF4020T-2R2N1R7	-	0.157 x 0.157	Refer to Data sheet for alt parts
11	1	L3	2.2μΗ	Inductor, SMT, 1.5A, 87 mW	TDK	VLF4012AT-2R2M1R5	-	0.137 x 0.147	Refer to Data sheet for alt parts
12	0	R2, R5, R17, R18, R21	Open	Resistor, chip, 1.16W, 1%	Std	Std	-	0603	
13	1	R10	499k	Resistor, chip, 1.16W, 1%	Std	Std	-	0603	
14	2	R15, R16	4.75k	Resistor, chip, 1.16W, 1%	Std	Std	-	0603	
15	2	R19, R20	0	Resistor, chip, 1.16W, 1%	Std	Std	-	0603	
16	8	R3, R6, R7, R11-R14, R22	100k	Resistor, chip, 1.16W, 1%	Std	Std	-	0603	
17	1	R8	10	Resistor, chip, 1.16W, 1%	Std	Std	-	0603	
18	1	R9	1.20M	Resistor, chip, 1.16W, 1%	Std	Std	-	0603	
19	1	R1	36k	Resistor, chip, 1.16W, 1%	Std	Std	-	0603	
20	1	R4	115k	Resistor, chip, 1.16W, 1%	Std	Std	-	0603	
		0144		College COST DD Managertage Cooled constability	0.0.11	V744 DO 114			
21	1	SW1	-	Switch, SPST, PB Momentary, Sealed, washable	C & K	KT11P2JM	-	0.245 x 0.251	
22	1	U1		IC Power Management IC	Texas Instruments	TPS65023RSB	-	QFN	

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